■ 外形图 Outline Drawing

- 采用无外封装叠片式技术，体积小
- 性能稳定，具有良好的温度特性、频率特性、电压特性、时间稳定性和防潮特性
- 可靠性高，自愈性好
- 无压电效应，无极性，无非线性失真
- 等效串联电阻低，噪音电平低
- 抗脉冲能力强
- 抗热冲击，抗机械冲击能力强

- Unc
- Stability versus temperature, frequency, voltage,time and humidity
- Reliable quality due to self-healing effect
- No piezoelectric effect, non-polar construction, non-linearity distortion
- Low ESR, low noise level
- high dv/dt ability
- No cracking under thermal impact or mechanical bump

0.2 ± 0.5